

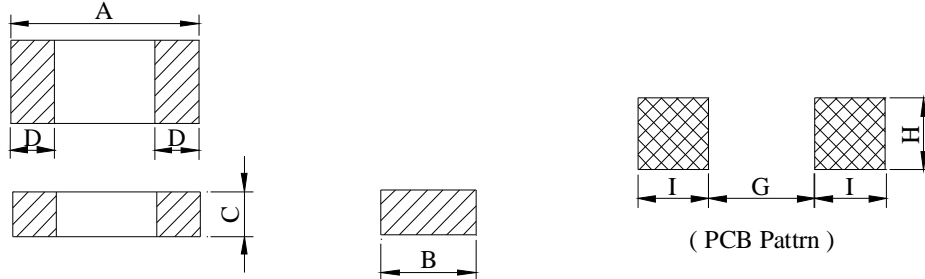
# SPECIFICATION FOR APPROVAL

REF : 20100706-A

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	SM□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

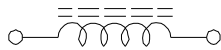
## I . CONFIGURATION & DIMENSIONS :



Unit : m/m

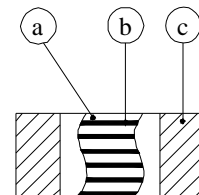
Series	A	B	C	D	G	H	I
SM2029	2.0±0.2	1.2±0.2	0.9±0.2	0.50±0.3	1.0	1.0	1.0
SM1608	1.6±0.2	0.8±0.2	0.8±0.2	0.30±0.2	0.7	0.7	0.7

## II . SCHEMATIC DIAGRAM :



## III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



## IV . GENERAL SPECIFICATION :

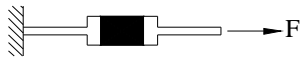
- a . Storage Conditions :

Electrical Performance temp : -55°C ~ +125°C

Terminal Solderability & Packages Material temp : -10°C ~ +40°C and RH 70% max.

- b . Operating temp. : -55°C ---- +125°C

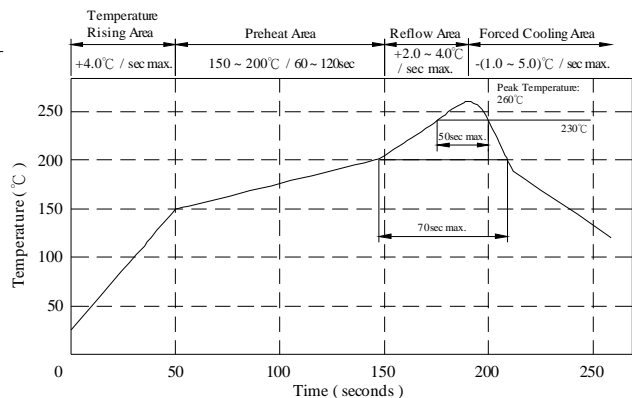
- c . Terminal Strength :



Type	F ( kgf )	time ( sec )
SM2029	0.6	30±5
SM1608	0.5	

- d . Solderability : Preheat : 150±25°C for 60 seconds  
 Solder : Sn96.5 / Ag3 / Cu0.5  
 or equivalent  
 Solder temp. : 260±5°C  
 Flux : Rosin  
 Dip time : 4±1 seconds

Peak Temp : 260°C max.  
 Max time above 230°C : 50sec max.  
 Max time above 200°C : 70sec max.



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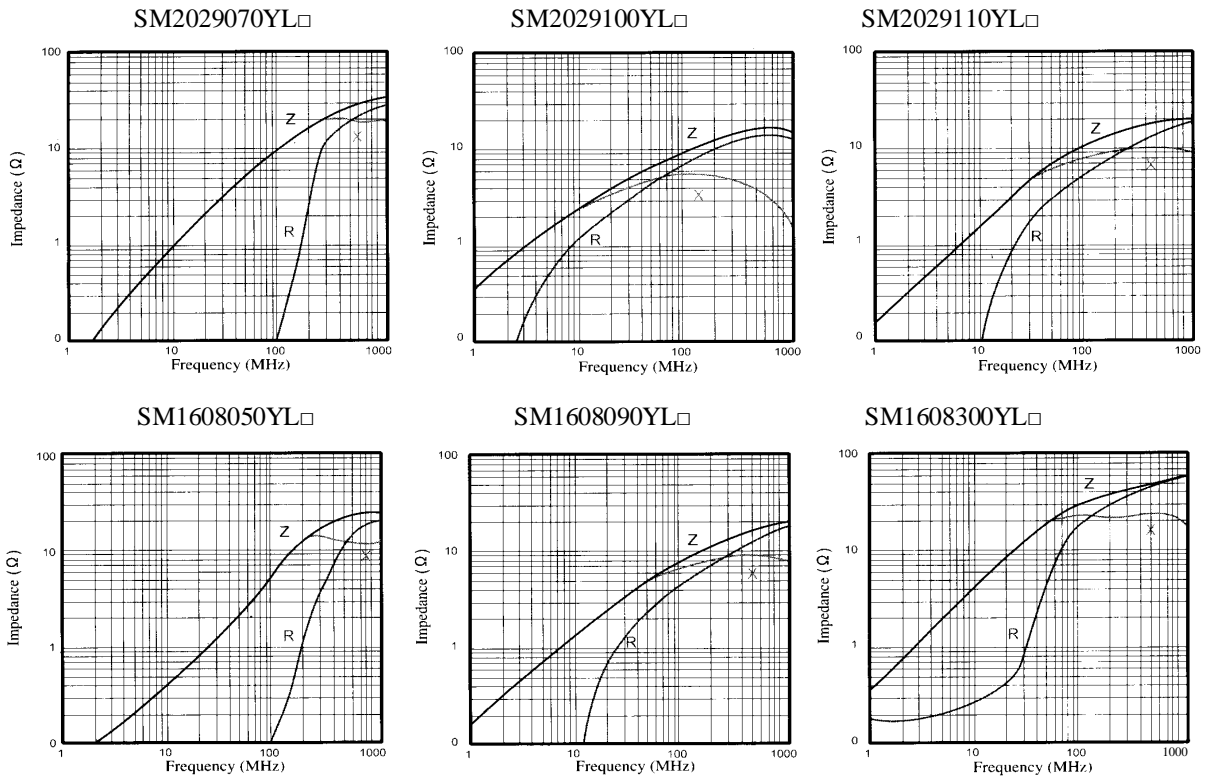
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		ABC'S ITEM NO.	

## V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
SM2029070YL□-□□□	7±25%	0.2	600
SM2029100YL□-□□□	10±25%	0.2	600
SM2029110YL□-□□□	11±25%	0.2	600
SM1608050YL□-□□□	5±25%	0.2	600
SM1608090YL□-□□□	9±25%	0.2	500
SM1608300YL□-□□□	30±25%	0.3	400

- 1). □ : Packaging Information... A : Bulk B : Taping Reel  
 2). "- □□□ " : Reference code



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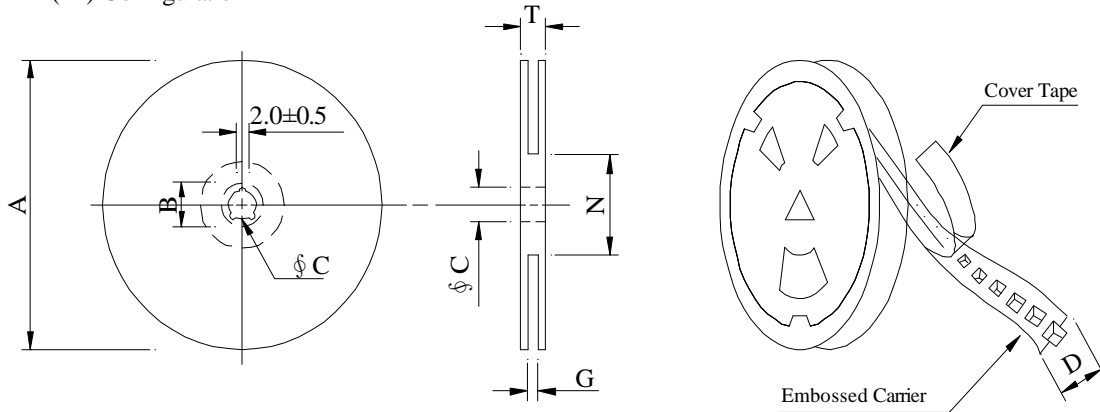
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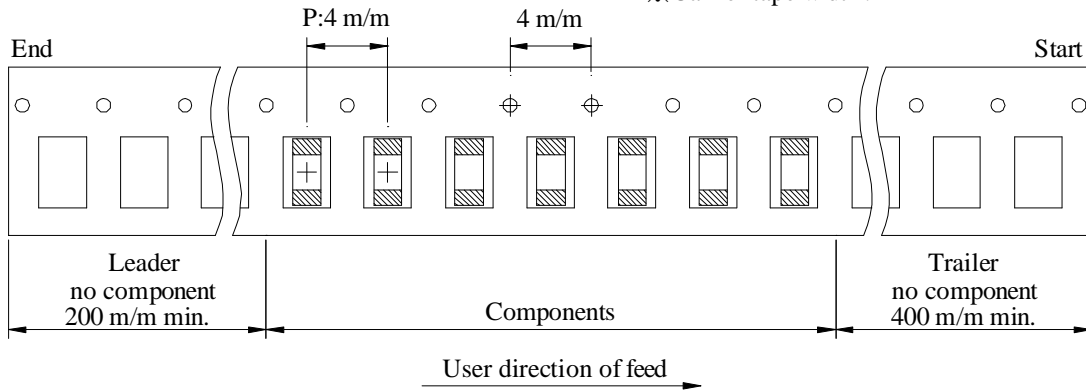
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		ABC'S ITEM NO.	

**VI . PACKAGING INFORMATION :**

( 1 ) Configuration



※Carrier tape width : D



( 2 ) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 <sup>+0</sup>	50 <sup>-0</sup>	12.5

( 3 ) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	QTY (k,pcs)	G.W. (Kg)	Size (cm)
SM1608	4,000	90	07 - 08	200	7.0	41 x 39 x 22
SM2029	4,000	120	07 - 08	200	8.5	41 x 39 x 22

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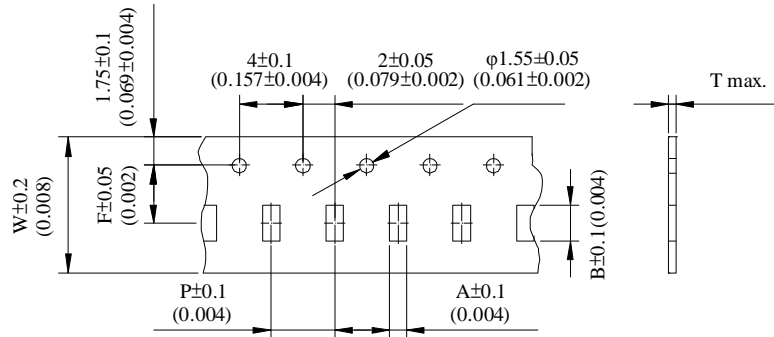
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( 4 ) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
SM1608	1.05	1.85	3.50	4.0	1.10	8.0	1
SM2029	1.50	2.30	3.50	4.0	1.10	8.0	1

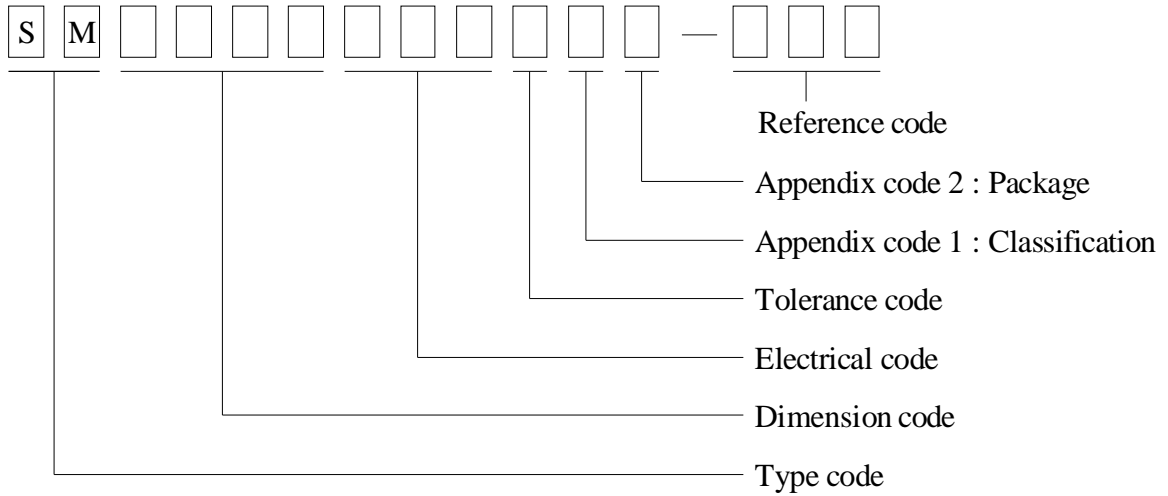
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## VII . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

L : Lead Free Standard products comply with RoHS' requirements

1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package QTY	Remark
A	T.B.D.	T.B.D.	
B	T / R ( Reel package )	4000 pcs	SM2029
	T / R ( Reel package )	4000 pcs	SM1608